



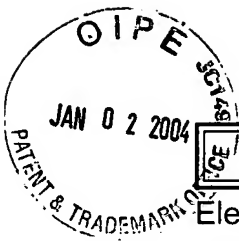
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Electronic Patent Application Submission
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EFS ID: 53068
Application ID: 10669820
Title of Invention: REINFORCED DIE PAD SUPPORT
STRUCTURE
First Named Inventor: Chung Tzu
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-09-24
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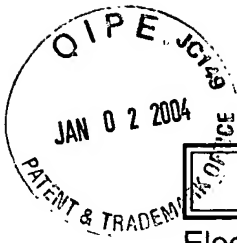
Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
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**TRANSMITTAL**

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Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE									
<p>Application Number: 10/669820 </p> <p>Date: 2003-09-24</p> <p>First Named Applicant: Chung Hsing Tzu</p> <p>Confirmation Number: 5197</p> <p>Attorney Docket Number: AMKOR090A</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids4-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids4-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids4-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number: 10/669820



Confirmation Number: 5197

First Named Applicant: Chung Tzu

Attorney Docket Number: AMKOR090A

Art Unit: 2811

Search string: (5909053 or 5915998 or 5917242 or 5939779
or 5942794 or 5951305 or 5959356 or 5969426
or 5973388 or 5976912 or 5977613 or 5977615
or 5977630 or 5981314 or 5986333 or 5986885
or 6001671 or 6013947 or 6018189 or 6020625
or 6025640 or 6031279 or RE36613 or 6034423
or 6040626 or 6043430 or 6060768 or 6060769
or 6072228 or 6075284 or 6081029 or 6084310
or 6087715 or 6087722 or 6100594 or 6113474
or 6118174 or 6118184 or 6130115 or 6130473
or RE36907 or 6133623 or 6140154 or 6143981
or 6169329 or 6177718 or 6181002 or 6184465
or 6184573 or 6194777).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	48	6184465	2001-02-06	CORISIS
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	50	6194777	2001-02-27	ABBOTT ET AL

Signature

Examiner Name	Date